



Material Content Data Sheet



Sales Product Name	TLE4242EJ			Issued	20. July 2018			
MA#	MA001193286							
Package	PG-DSO-8-27			Weight*	84.01 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.033	2.42	2.42	24198	24198
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.728	0.87		8662	
wire	non noble metal	copper	7440-50-8	29.548	35.17	36.09	351696	360899
	noble metal	gold	7440-57-5	0.122	0.14	0.14	1449	1449
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1177
encapsulation	plastics	epoxy resin	-	4.547	5.41		54121	
	inorganic material	silicondioxide	60676-86-0	44.777	53.30	58.83	532973	588271
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8274	8274
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8624	8624
glue	plastics	epoxy resin	-	0.174	0.21		2071	
	noble metal	silver	7440-22-4	0.522	0.62	0.83	6214	8285
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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